

JAN 21 2004

OFFICIAL
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DN 51343

In re application of:

Seita et al.

:

Serial No.: 10/027,919

:

Filed: December 20, 2001

: Group Art Unit: 1753

For: ELECTROLYTIC COPPER PLATING
SOLUTION AND METHOD FOR
CONTROLLING THE SAME

: Examiner: Edna Wong

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

In response to the Official Action mailed on October 21, 2003, Applicants submit the following amendments and remarks.

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.